

Abstract

A chip arrangement comprising a first chip having at least one first signal interface with first coupling elements arranged along a first line in a first number density and at least one second chip with at least one second signal interface with second coupling elements arranged along a second line in a second number density, where the first and second coupling elements permit contactless signal transmission between the first and second signal interfaces, where the two chips are so arranged relative to each other that coupling elements of the first and second signal interfaces can contactlessly transmit signals with each other, where the longitudinal extent of at least one of the signal interfaces along the line associated therewith is greater than the length of the overlap of the two longitudinal extents, and where one of the signal interfaces has a greater number density of coupling elements than the other.